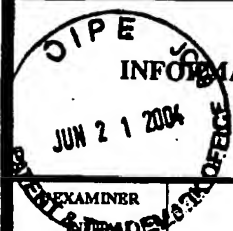
 <p>INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)</p>		Docket Number (Optional) 31550-1001		Application Number 10/799,905	
		Applicant(s) Thomas J. O'Keefe, et al.			
		Filing Date March 12, 2004		Group Art Unit 1762 1753	
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EXAMINER William Leader		DATE CONSIDERED 7/3/2007			
<p>*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>					



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(Use several sheets if necessary)

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Applicant(s)

Thomas J. O'Keefe, et al.

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Substitute for form 1449A/PTO			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete if Known	
		Application Number	10/799,905
		Filing Date	March 12, 2004
		First Named Inventor	O'Keefe et al.
		Art Unit	1762 1753
		Examiner Name	N/A
Sheet	1	of	2
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				First Named Inventor	O'Keefe et al.
				Art Unit	1762 1753
				Examiner Name	N/A
Sheet	2	of	2	Attorney Docket No: 31550-1001	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.†	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T‡
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Substitute Disclosure Statement Form (PTO-1449)

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